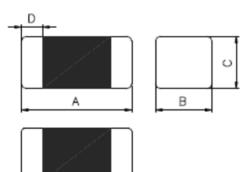


## **FEATRLRES**

- Monolithic inorganic material construction.
- Closed magnetic circuit avoids crosstalk.
- S.M.T. type.
- Suitable for reflow soldering.
- Shapes and dimensions follow E.I.A. spec.
- Available in various sizes.
- Excellent solder ability and heat resistance.
- High reliability.
- 100% Lead(Pb) & Halogen-Free and RoHS compliant.

## CONFIGRLRATIONS & DIMENSIONS ( unit in mm )



Size	А	В	С	D
FCM1608	1.60±0.15	0.80±0.15	0.80±0.15	0.30±0.20

### **ELECTRICAL CHARACTERISTICS**

Number	Impedance (Ω)	Test Frequency	DC Resistance ( $\Omega$ )	Rated Current (mA)
Number		(MHz)	max.	max.
FCM1608KF-300T07	30±25%	100	0.20	700
FCM1608KF-600T07	60±25%	100	0.20	700
FCM1608KF-121T06	120±25%	100	0.25	600
FCM1608KF-151T06	150±25%	100	0.25	600
FCM1608KF-221T05	220±25%	100	0.30	550
FCM1608KF-301T05	300±25%	100	0.35	500
FCM1608KF-471T03	470±25%	100	0.45	350
FCM1608KF-601T03	600±25%	100	0.50	350
FCM1608KF-102T02	1000±25%	100	0.70	200
FCM1608HF-152T02	1500±25%	100	1.00	200
FCM1608HF-202T01	2000±25%	100	1.20	150
FCM1608CF-100T07	10±25%	100	0.20	700
FCM1608CF-300T06	30±25%	100	0.25	600
FCM1608CF-100T07	10±25%	100	0.20	700



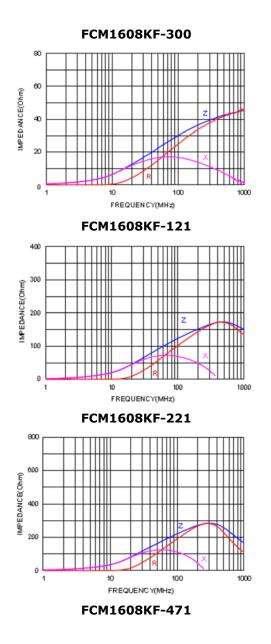
SA-SP-001

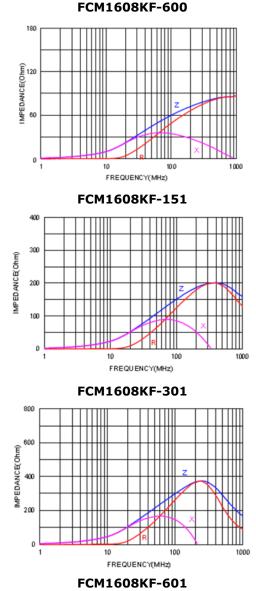
FCM1608CF-600T06	60±25%	100	0.30	600
FCM1608CF-121T03	120±25%	100	0.40	300
FCM1608CF-151T03	150±25%	100	0.40	300
FCM1608CF-221T02	220±25%	100	0.60	250
FCM1608CF-301T02	300±25%	100	0.80	200
FCM1608CF-471T02	470±25%	100	0.85	200
FCM1608CF-601T01	600±25%	100	1.20	150
FCM1608CF-102T00	1000±25%	100	1.50	80

Rated current: based on temperature rise test

In compliance with EIA 595

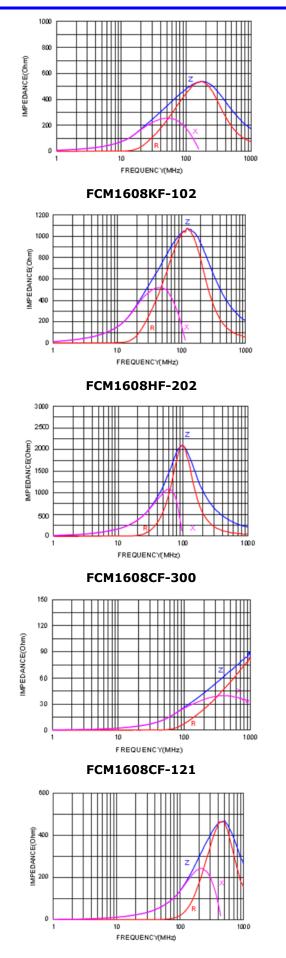
# Impedance Frequency Characteristics(Typical)

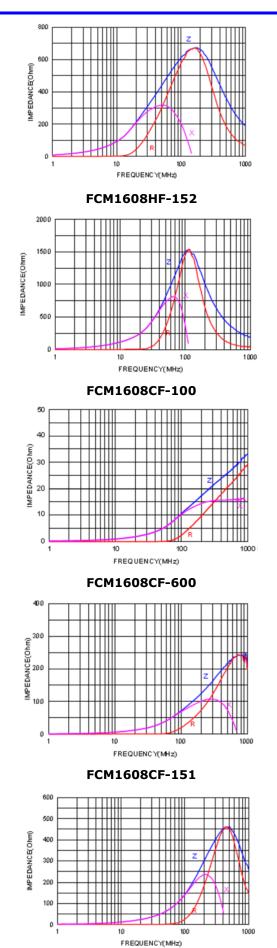




FCM1608KF-600



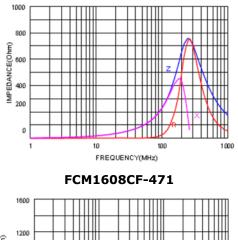


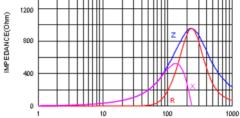


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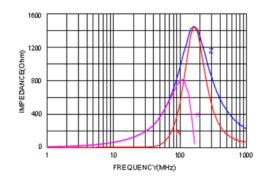


#### FCM1608CF-221

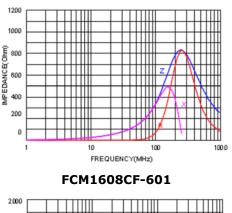


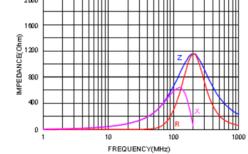






FCM1608CF-301





## **Reliability and Test Condition**

Item	Performance	Test Condition
Operating temperature	-40~+125 $^\circ\!\!\mathbb{C}$ (Including self - temperature rise)	
Storage temperature	110~+40℃,50~60%RH (Product with taping) 240~+125℃ (on board)	
Electrical Performance Test		



Refer to standard electrical characteristics list	HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter.		
	CH16502,Agilent33420A Micro-Ohm Meter.		
Approximately∆L30%	Saturation DC Current (Isat) will cause L0 to drop		
Approximately △T40°C	Heat Rated Current (Irms) will cause the coil temperature rise $\triangle T(\degree C)$ . 1.Applied the allowed DC current 2.Temperature measured by digital surface thermometer		
	Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles) Temperature : 125±2°C (Inductor) Applied current : rated current Duration : 1000±12hrs Measured at room temperature after placing for 24±2 hrs Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC		
	J-STD-020DClassification Reflow Profiles Humidity : 85±2 * R.H, Temperature : 85°C ±2°C Duration : 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs		
Appearance : No damage. Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD- 020DClassification Reflow Profiles 1. Baked at50℃ for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs. 3. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs,keep at 25℃ for 2 hrs then keep at -10℃ for 3 hrs 4. Keep at 25℃ 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.		
	Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD- 020DClassification Reflow Profiles Condition for 1 cycle Step1 : $-40\pm^2$ °C 30 $\pm$ 5min Step2 : $25\pm^2$ °C $\leq$ 0.5min Step3 : $125\pm^2$ °C 30 $\pm$ 5min Number of cycles : 500 Measured at room temperature after placing for 24 $\pm$ 2 hrs		
	Oscillation Frequency: 10 ~ 2K ~ 10Hz for 20 minutes Equipment : Vibration checker Total Amplitude:1.52mm±10% Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations).		
	Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm <0805 inch(2012mm):40x100x0.8mm Bending depth: >=0805 inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.		
Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	Type   Peak value (g's)   Normal duration (D) (ms)   Wave form   Velocity change (Vi)ft/sec     0UD   50   44   Ust faile   44.0		
	SMD   50   11   Half-sine   11.3     Lead   50   11   Half-sine   11.3		
More than 95% of the terminal electrode should be covered with solder.	Preheat: 150°C,60sec.₀ Solder: Sn96.5% Ag3% Cu0.5% Temperature: 245±5°C ∘ Flux for lead free: Rosin. 9.5% ∘ Dip time: 4±1sec ∘ Depth: completely cover the termination Depth: completely cover the termination		
	Temperature (°C) Time(s) ramp/immersion Number of		
	Approximately △T40°C   Appearance : No damage.   Inductance : within±10% of initial value   Q : Shall not exceed the specification value.   RDC : within±15% of initial value and shall not exceed the specification value   RDC : within±15% of initial value and shall not exceed the specification value   RDC : within±15% of initial value   Q : Shall not exceed the specification value.   RDC : within±15% of initial value   Inductance : within±15% of initial value   RDC : within ±15% of initial value   More than 95% of the terminal electrode should		



	Appearance : No damage. Impedance : within±15% of initial value Inductance : within±10% of initial value 0 : Shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD- 020DClassification Reflow Profiles With the component mounted on a PCB with the device to be tested, apply a force( $\sim$ 0805:1kg, <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.
Terminal Strength		DUT substrate press tool

Note : When there are questions concerning measurement result : measurement shall be made after  $48 \pm 2$  hours of recovery under the standard condition.